



# 100% Material Declaration Data Sheet CPG56

PK100 (v1.2) September 28, 2006

Material Declaration Data Sheet

**Average Weight: 0.1 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.00215</b>	<b>2.15%</b>
	Silicon	7440-21-3	100.00		0.00215	
<b>Die Attach Material</b>					<b>0.0005</b>	<b>0.50%</b>
	Silver	7440-22-4	78.00		0.00039	
	Resin (EP)	Trade Secret	22.00		0.00011	
<b>Encapsulant</b>					<b>0.03956</b>	<b>39.56%</b>
	Epoxy Resins	Trade Secret	6.00		0.0023736	
	Phenolic Resins	Trade Secret	6.00		0.0023736	
	Carbon Black	1333-86-4	0.50		0.0001978	
	Silica	60676-86-0	84.00		0.0332304	
	Bismuth	7440-69-9	Max 1.00		0.0003956	
	Metal Hydroxide	Trade Secret	2.50		0.000989	
<b>Laminate</b>					<b>0.0126</b>	<b>12.60%</b>
	Bismaleimide/Triazine Board	13676-54-5 / 25722-66-1	72.285		0.00910791	
	Copper	7440-50-8	9.780		0.00123228	
	Nickel	7440-02-0	7.890		0.00099414	
	Gold	7440-57-5	1.140		0.00014364	
	Antimony Pentoxide	1314-60-9	0.005	Flame Retardant	0.00000063	
	Brominated Resin	68541-56-0	8.900	Flame Retardant	0.0011214	
<b>Bond Wire</b>					<b>0.00023</b>	<b>0.23%</b>
	Gold	7440-57-5	100.00		0.00023	
<b>Solder Balls</b>					<b>0.04496</b>	<b>44.96%</b>
	Tin	7440-31-5	95.50		0.0429368	
	Silver	7440-22-4	4.00		0.0017984	
	Copper	7440-50-8	0.50		0.0002248	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/20/06	1.0	Initial release.
6/01/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.